



# Ultra-small package High-precision Voltage Detector with delay

# circuit, ME2805 Series

## **General Description**

**ME2805 Series** is a series of high-precision voltage detectors with a built-in delay time generator of fixed time developed using CMOS process. Internal oscillator and counter timer can delay the release signal without external parts. Detect voltage is extremely accurate with minimal temperature drift. CMOS output configurations are available.

## **Features**

- Highly accuracy: ±1%
- Low power consumption: TYP 0.9uA (V<sub>DD</sub>=3V)
- Detect voltage range : 1.0V~6.5V in 0.1V increments
- Operating voltage range: 0.7V~7V
- Detect voltage temperature characteristics: TYP±100ppm/°C
- Output configuration: CMOS

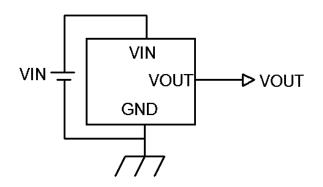
## **Typical Application**

- Power monitor for portable equipment such as notebook computers, digital still cameras, PDA, and cellular phones
- Constant voltage power monitor for cameras, video equipment and communication devices.
- Power monitor for microcomputers and reset for CPUs.
- System battery life and charge voltage monitors

## Package

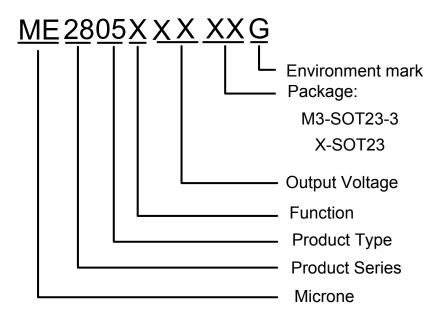
• 3-pin SOT23-3、SOT23

## **Typical Application Circuit**





# **Selection Guide**

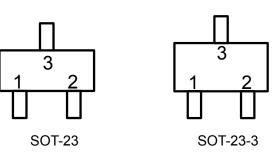


product series	product description				
ME2805A263M3G	V <sub>OUT</sub> =2.63V; Rising edge detection; Package: SOT23-3				
ME2805A263XG	V <sub>OUT</sub> =2.63V; Rising edge detection; Package: SOT23				
ME2805A293M3G	V <sub>OUT</sub> =2.93V; Rising edge detection; Package: SOT23-3				
ME2805A293XG	V <sub>OUT</sub> =2.93V; Rising edge detection; Package: SOT23				
ME2805A308XG	V <sub>OUT</sub> =3.08V; Rising edge detection; Package: SOT23				
ME2805A463XG	V <sub>OUT</sub> =4.63V; Rising edge detection; Package: SOT23				

**NOTE:** If you need other voltage and package, please contact our sales staff.



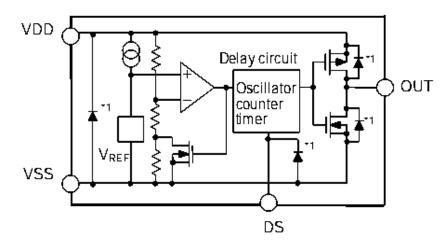
# **Pin Configuration**



# Pin Assignment

PIN Number	Pin Name	Function	
SOT-23-3/SOT-23	Fill Naille	Function	
1	VSS	Ground	
2 VOUT Output Voltage		Output Voltage	
3 VDD Input Voltage		Input Voltage	

## **Block Diagram**



\*1. Parasitic diode

# **Absolute Maximum Ratings**

PARAMETER			SYMBAL	RATINGS	UNITS
V <sub>IN</sub> Input Voltage			V <sub>IN</sub>	8	V
Output Current		I <sub>OUT</sub>	50	mA	
Output Voltage		CMOS	V <sub>OUT</sub>	V <sub>OUT</sub> GND-0.3~V <sub>IN</sub> +0.3	
Continuous Total Power		SOT-23-3	– Pd	300	mW
Dissipation		SOT-23	- Fu	250	11177
Operating Ambient Temperature		T <sub>Opr</sub>	-40~+85	°C	
Storage Temperature		T <sub>stg</sub>	-40~+125	°C	
Soldering temperature and time			T <sub>solder</sub>	<b>260℃, 10s</b>	
			MM	400	V
ESD		HBM	4000	V	



# **Electrical Characteristics**

(-V<sub>DET</sub>(S)=1.0V to  $6.5V\pm2\%$ , Ta= $25^{\circ}C$ , unless otherwise noted)

Parameter	Symbol	Conditions	Min.	Тур	Max.	Units	Test circuit	
Detect Voltage (Output Voltage)	-VDET	-	-VDET (S) ×0.99	-VDET(S)	-VDET(S) ×1.01	V	1	
Hysteresis Range	VHYS	-	0.03	0.06	0.1	V		
		VDD=3V (below 2.5V)	-	0.9	1.5			
Supply Current	ISS	VDD=5V (2.5V-4.5V)	-	1.4	2.8	uA 2	2	
		VDD=7V (4.5V-6.5V)	-	1.8	3.6			
Output Current	lout N-ch	VDS=0.5V VDD=0.7V	0.01	0.19		mA	3	
	lout P-ch	VDS=0.5V VDD=7V	1.7	3.4		mA	4	
Operating voltage	VDD	-	0.7	-	7	V	1	
Delay time	Td1	VDD=-VDET+1V DS low	130	200	290	ms	1	
	Td2	VDD=-VDET+1V DS high	110	220	330	us	5	
Temperature characteristics	$\frac{\Delta - VDET}{\Delta Ta \bullet - VDET}$	∆ <i>Ta</i> <b>=_40</b> °C ~ 85°C	-	±100	±350	<b>ppm/℃</b>	1	

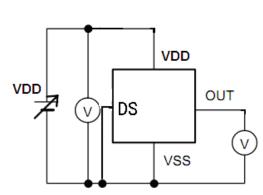
Note: 1、-VDET(S) : Specified Detection Voltage value

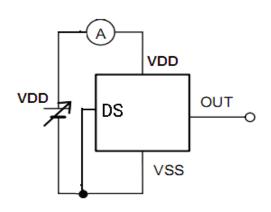
2、-VDET: Actual Detection Voltage value

3、Release Voltage: +VDET=-VDET+VHYS

## **Test Circuits:**

1.

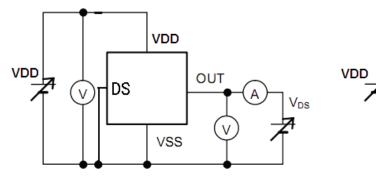


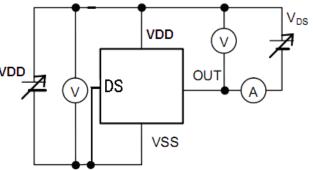


2.

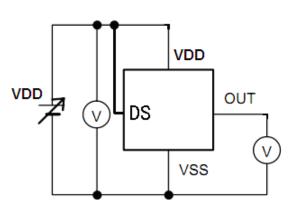


3.





5.



# **Functional Description:**

## 1. Basic Operation: CMOS Output (Active Low)

1-1. When the power supply voltage (VDD) is higher than the release voltage (+VDET), the Nch transistor is OFF and the Pch transistor is ON to provide VDD (high) at the output. Since the Nch transistor N1 in Figure 1 is OFF, the

$$\frac{(R_B + R_C) \bullet VDD}{P}$$

comparator input voltage is  $R_A + R_B + R_C$ 

1-2. When the VDD goes below +VDET, the output provides the VDD level, as long as VDD remains above the detection voltage (–VDET). When the VDD falls below –VDET (point A in Figure 2), the Nch transistor becomes ON, the Pch transistor becomes OFF, and the VSS level appears at the output. At this time the Nch

 $\frac{R_B \bullet VDD}{R + R}$ 

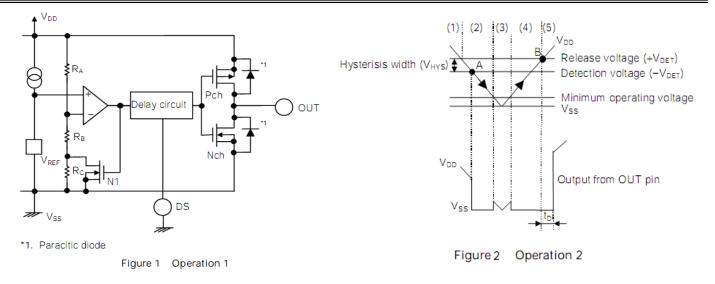
transistor N1 in Figure 1 becomes ON, the comparator input voltage is changed to  $\overline{R_A + R_B}$ .

- 1-3. When the VDD falls below the minimum operating voltage, the output becomes undefined, or goes to VDD when the output is pulled up to VDD.
- 1-4. The VSS level appears when VDD rises above the minimum operating voltage. The VSS level still appears even when VDD surpasses the –VDET, as long as it does not exceed the release voltage +VDET.
- 1-5. When VDD rises above +VDET (point B in Figure 2), the Nch transistor becomes OFF and the Pch transistor becomes ON to provide VDD at the output. The VDD at the OUT pin is delayed for Td due to the delay circuit.

V04



# ME2805



#### 2. Delay Circuit

#### 2-1. Delay Time

The delay circuit delays the output signal from the time at which the power voltage (VDD) exceeds the release voltage (+VDET) when VDD is turned on. The output signal is not delayed when the VDD goes below the detection voltage (–VDET). (Refer to Figure 2.) The delay time ( $t_D$ ) is a fixed value that is determined by a built-in oscillation circuit and counter.

#### 2-2. DS Pin (ON/OFF Switch Pin for Delay Time)

The DS pin should be connected to Low or High. When the DS pin is High, the output delay time becomes short since the output signal is taken from the middle of counter circuit (Refer to Figure 3).

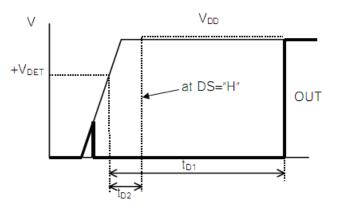


Figure 3



## **Directions for use:**

- Please use this IC within the stated maximum ratings. Operation beyond these limits may cause degrading or permanent damage to the device.
- 2、When a resistor is connected between the V<sub>DD</sub> pin and the input with CMOS output configurations, oscillation may occur as a result of voltage drops at R<sub>IN</sub> if load current(I<sub>OUT</sub>) exists.(refer to the Oscillation Description(1) below)
- 3、When a resistor is connected between the V<sub>DD</sub> pin and the input with CMOS output configurations, oscillation may occur as a result of through current at the time of voltage release even if load current(I<sub>OUT</sub>) does not exist. (refer to the Oscillation Description(2) below)
- 4、With a resistor connected between the V<sub>DD</sub> and the input, detect and release voltage will rise as a result of the IC's supply current flowing through the V<sub>DD</sub> pin.
- 5. In order to stabilize the IC's operations, please ensure that V<sub>DD</sub> pin's input frequency's rise and fall times are more than several u Sec/V.

# **Oscillation Description:**

1. Output current oscillation with the CMOS output configuration

When the voltage applied at IN rises, release operations commence and the detector's output voltage increase. Load current( $I_{OUT}$ ) will flow at  $R_L$ . Because a voltage drop( $R_{IN}*I_{OUT}$ ) is produces at the  $R_{IN}$  resistor, located between the input(IN) and the  $V_{DD}$  pin. The load current will flow via the IC's pin. The voltage drop will also lead to a fall in the voltage level at the  $V_{DD}$  pin. When the  $V_{DD}$  pin voltage level falls below the detect voltage level, detect operations will commence. Fllowing detect operations, load current flow will cease and since voltage drop at  $R_{IN}$  will disapper, the voltage level at the  $V_{DD}$  pin will rise and release operations will begin over again. Oscillation may occur with this "release-detect-release" repetition. Further, this condition will also appear via means of a similar mechanism during detect operations.

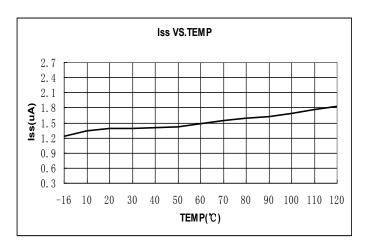
2. Oscillation as a result of through current Since the ME2805 series are CMOS IC's, through current will flow when the IC's internal circuit switching operates(during release and detect operations). Consequently, oscillation is liable to occur as a result of drops in voltage at the through current's resistor(R<sub>IN</sub>) during release voltage operations.(refer to diagram 2) since hysteresis exists during detect operations, oscillation is unlikely to occur.



## **Type Characteristics**

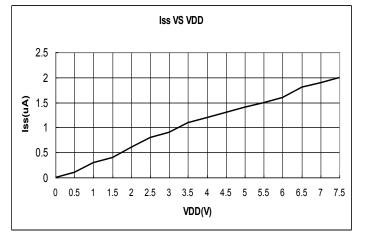
## 1、SUPPLY CURRENT VS. AMBIENT TEMPERATURE

#### VDD=5V,-VDET=2.63V

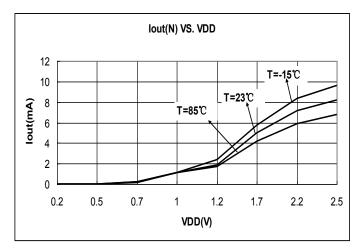


## $\mathbf{2}$ $\smallsetminus$ SUPPLY CURRENT VS. INPUT VOLTAGE

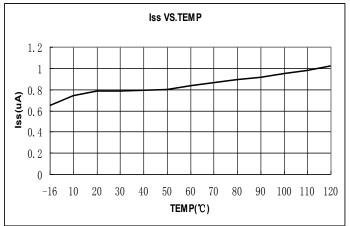
#### -VDET=2.63V (T=25℃)



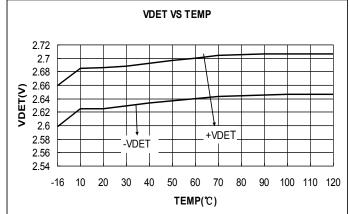
#### 4、 OUTPUT CURRENT VS. INPUT VOLTAGE N-ch VDS=0.5V,-VDET=2.63V



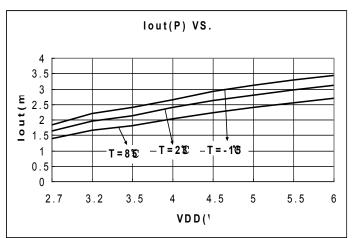
#### VDD=2.5V,-VDET=2.63V



#### 3 DETECT, RELEASE VOLTAGE VS. AMBIENT TEMPERATURE -VDET=2.63V



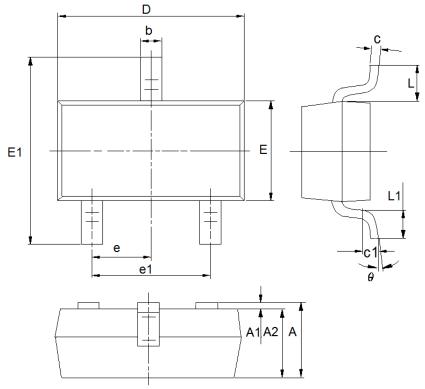
## P-ch VDS=0.5V,-VDET=2.63V





# **Packaging Information**

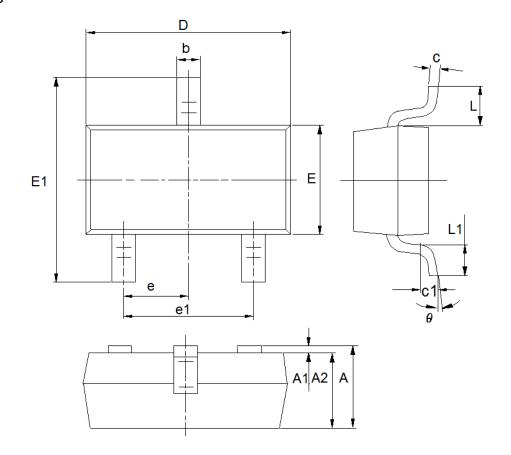
## • SOT23



DIM	Millimeters		Inches		
N	Min	Max	Min	Max	
А	0.9	1.2	0.0354	0.0472	
A1	0	0.14	0.0000	0.0055	
A2	0.9	1.05	0.0354	0.0413	
b	0.28	0.52	0.0110	0.0205	
С	0.07	0.23	0.0028	0.0091	
D	2.8	3.0	0.1102	0.1181	
e1	1.8	2.0	0.0709	0.0787	
E	1.2	1.4	0.0472	0.0551	
E1	2.2	2.6	0.0866	0.1024	
е	0.95(	0.95(TYP)		·(TYP)	
L	0.55(TYP)		0.0217	(TYP)	
L1	0.25	0.55	0.0098	0.0217	
θ	0	8°	0.0000	8°	
c1	0.25(TYP)		0.0098	B(TYP)	



## • SOT23-3



DIM	Millimeters		Inches		
DIM	Min	Max	Min	Max	
Α	0.9	1.2	0.0354	0.0472	
A1	0	0.14	0.0000	0.0055	
A2	0.9	1.05	0.0354	0.0413	
b	0.28	0.52	0.0110	0.0205	
С	0.07	0.23	0.0028	0.0091	
D	2.8	3.0	0.1102	0.1181	
e1	1.8	2.0	0.0709	0.0787	
E	1.2	1.4	0.0472	0.0551	
E1	2.2	2.6	0.0866	0.1024	
е	0.95(TYP)		0.0374(TYP)		
L	0.55(TYP)		0.0217(TYP)		
L1	0.25	0.55	0.0098	0.0217	
θ	0	8°	0.0000	8°	
c1	0.25(TYP)		0.0098	B(TYP)	



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